



## **SUSS MICROTEC INVESTOR PRESENTATION**

**January 2014**

This presentation contains forward-looking statements relating to the business, financial performance and earnings of SUSS MicroTec AG and its subsidiaries and associates. Forward-looking statements are based on current plans, estimates, projections and expectations and are therefore subject to risks and uncertainties, most of which are difficult to estimate and which in general are beyond the control of SUSS MicroTec AG. Consequently, actual developments as well as actual earnings and performance may differ materially from those which explicitly or implicitly assumed in the forward-looking statements. SUSS MicroTec AG does not intend or accept any obligation to publish updates of these forward-looking statements.

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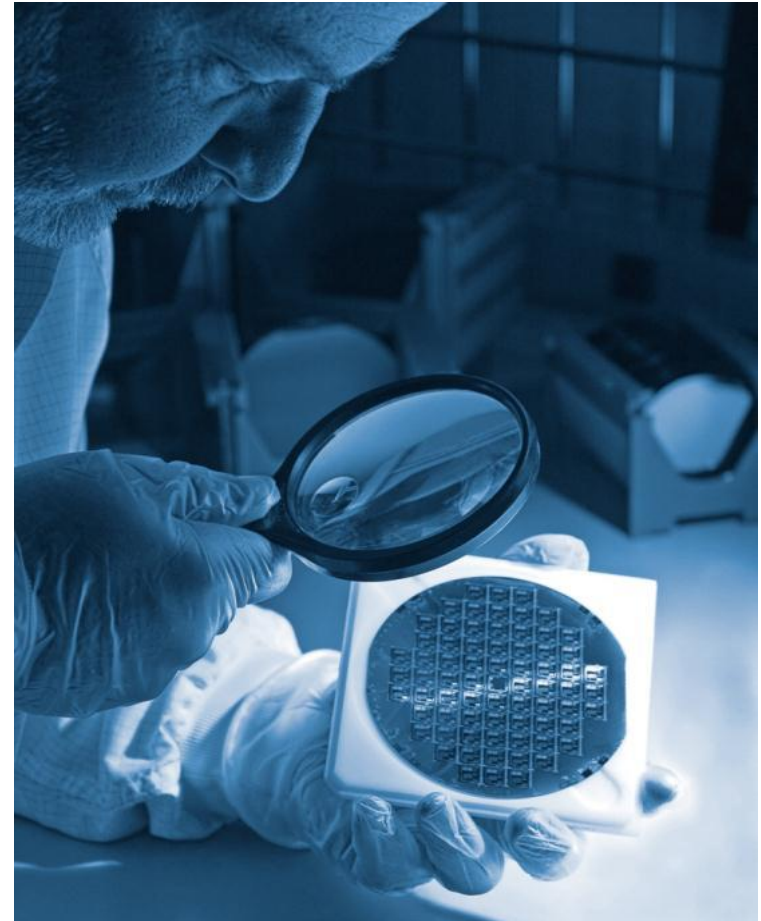
- I. SUSS MicroTec at a Glance**
- II. Products and Markets
- III. Growth Opportunities
- IV. Enhanced Lithography Portfolio
- V. Financials
- VI. Outlook

- + SUSS MicroTec: A global leader in semiconductor equipment
- + Our equipment and process solutions create the micro structures that build and connect micro electronic devices
- + We are focused on high growth market segments: Semiconductors, MEMS, LEDs

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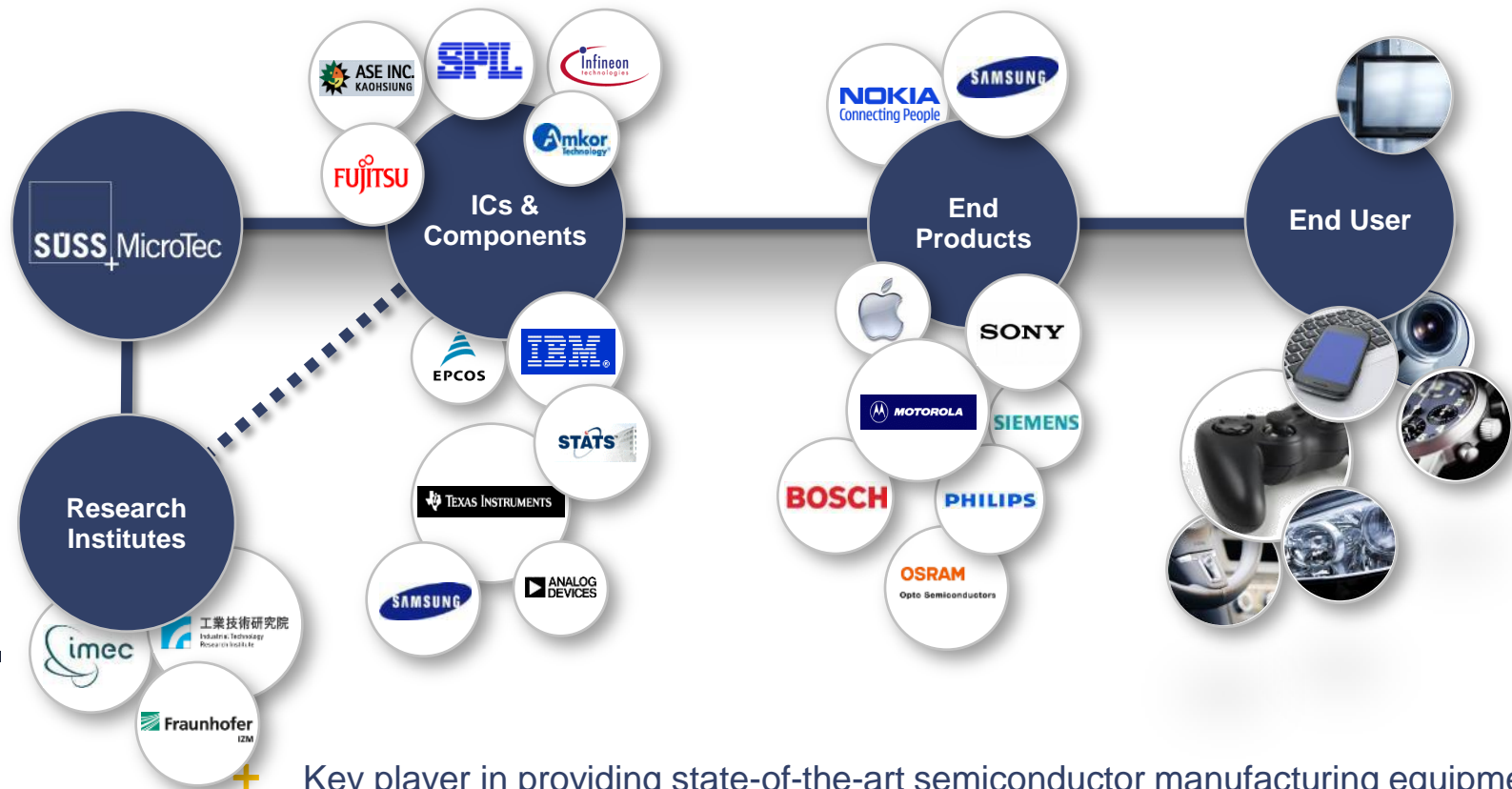
## + Key Data:

- Stock Exchange Symbol: SMHN
- Share price\*: 6.46 €
- Market Cap\*: 123 € million
- Net Cash, September 30, 2013: 21.9 € million



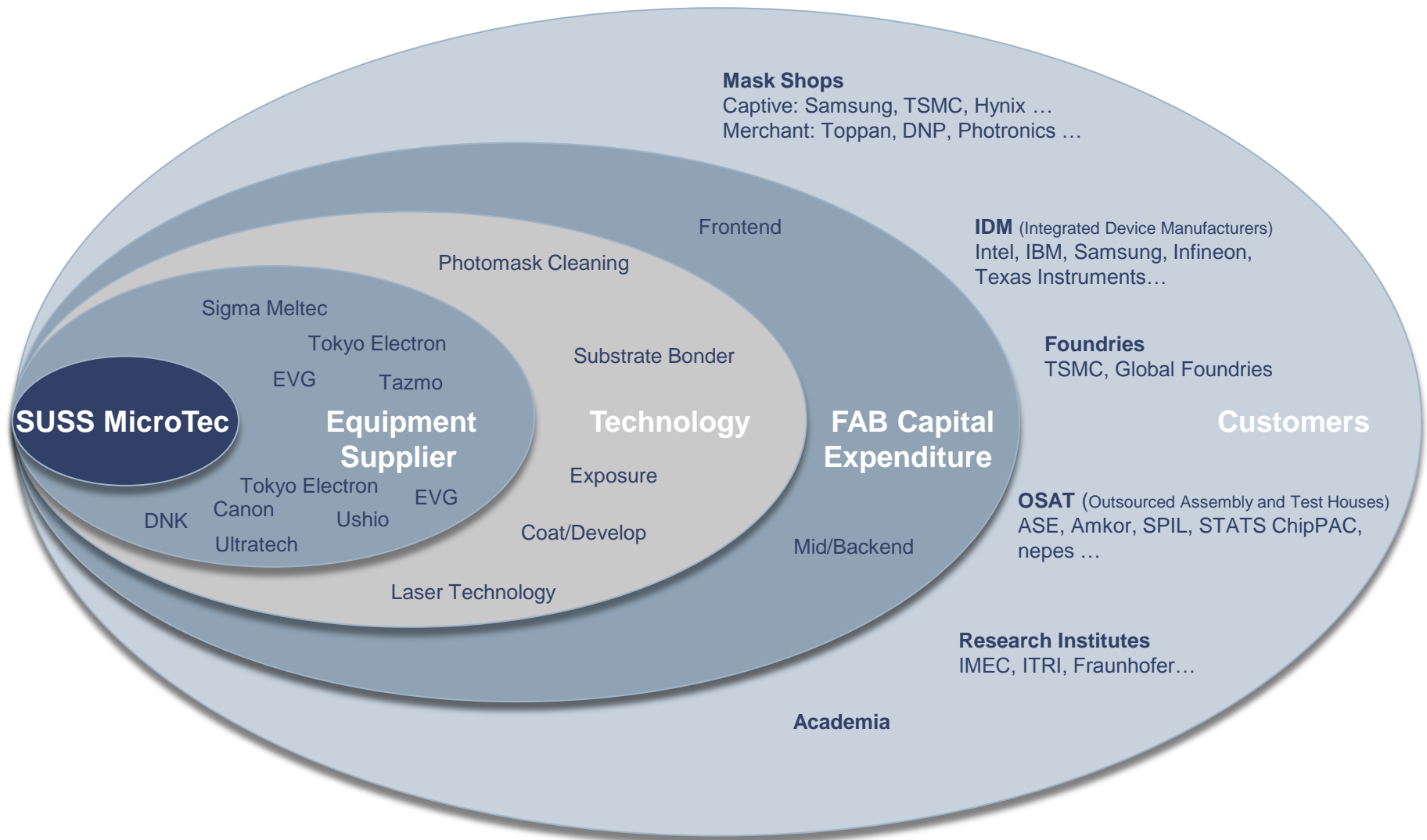
\* December 30, 2013



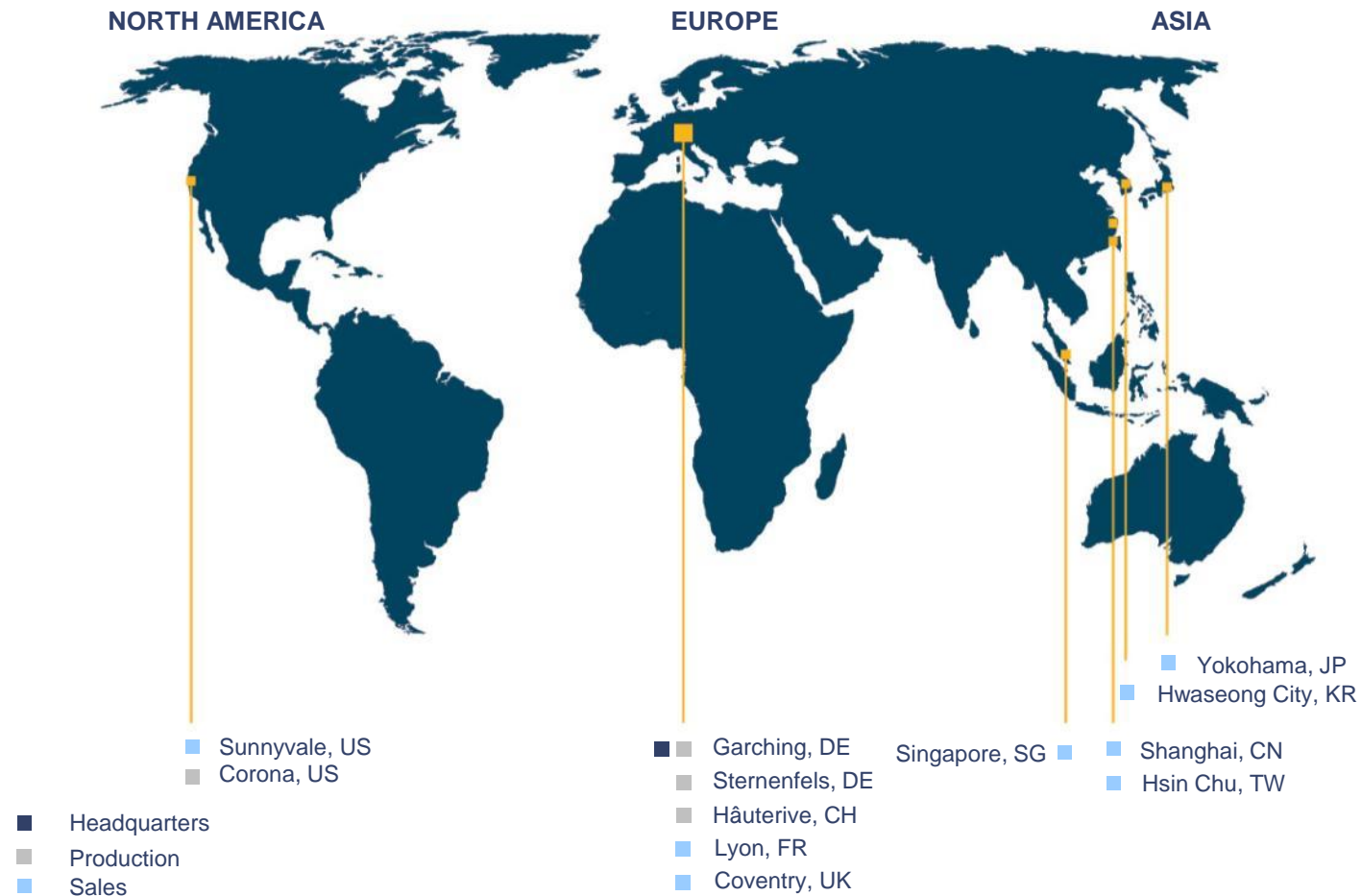


- + Key player in providing state-of-the-art semiconductor manufacturing equipment
- + Development of highly innovative process solutions with industry and R&D partners
- + Components for electronic devices like cell phones, PCs and tablet computers are produced on SUSS MicroTec's equipment

# THE SEMICONDUCTOR MARKET



# SUSS MICROTEC – A GLOBAL PLAYER



## Germany



### Garching

- + SUSS MicroTec HQ
- + Development/production:
  - **Mask Aligner**
  - **Bond Aligner**
- + Core competencies:
  - **Exposure**  
(proximity exposure)
  - **Alignment**



### Sternenfels

- + Development/production :
  - **Bonder**
  - **Coater and Developer**
  - **Photomask Equipment**
- + Core competencies:
  - **Wet processing**
  - **Wafer bonding**

## USA



### Corona

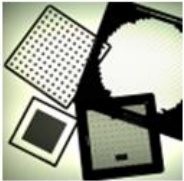
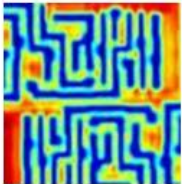
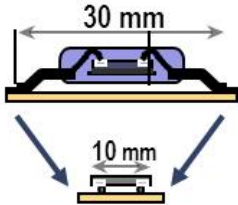
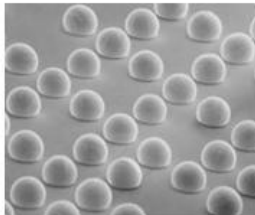
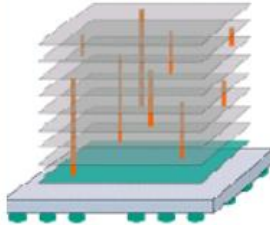
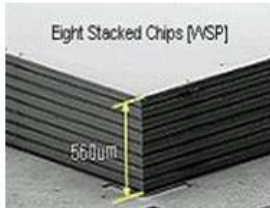

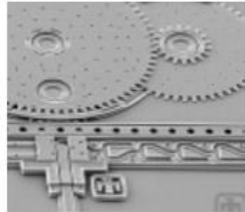
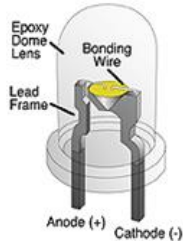

- + Development/production:
  - **Stepper/Scanner**
  - **Laser Processing**
- + Core competencies:
  - **Exposure**  
(UV projection lithography)
  - **Laser Ablation**



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- II.** Products and Markets
- III.** Growth Opportunities
- IV.** Enhanced Lithography Portfolio
- V.** Financials
- VI.** Outlook

Semiconductors			Sensors	Lighting
Mask Manufacturing Photomask Cleaning	Advanced Packaging Micro-Bumping	3D Integration/Stacking	<b>MEMS</b> Computing, Automotive, Medical Applications ...	<b>LED</b> General Lighting, HB and UHB LED
  	  	  	  	  

# SEGMENTS, PRODUCTS AND MARKETS



- + Reevaluation of the business situation in permanent bonding**
  - ongoing losses
  - expansion of the restructuring measures, which have been taken in Q2, 2013
-  **Cease production of cluster systems for permanent bonding applications**
- + Losses of the Substrate Bonding Division will be reduced significantly**
- + The successful manual permanent bonding systems are not affected**
- + Extraordinary expenses of € 6.0 million in Q2 2013**
  - € 4.6 million value adjustments on capitalized development costs from the years prior to 2008, demonstration equipment, and other inventories
  - € 1.4 million provisions for commitments and other agreements
- + Extraordinary expenses of € 8.3 million will be taken in Q4 2013:**
  - € 6.7 million for write-offs on raw materials, unfinished goods and demonstration tools
  - € 1.6 million for precautionary formed accruals for single customer projects
- + Cumulative expenses for the restructuring of permanent bonding in 2013 will amount to approximately € 14.3 million**



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# TECHNOLOGY EVOLUTION



~1985...today



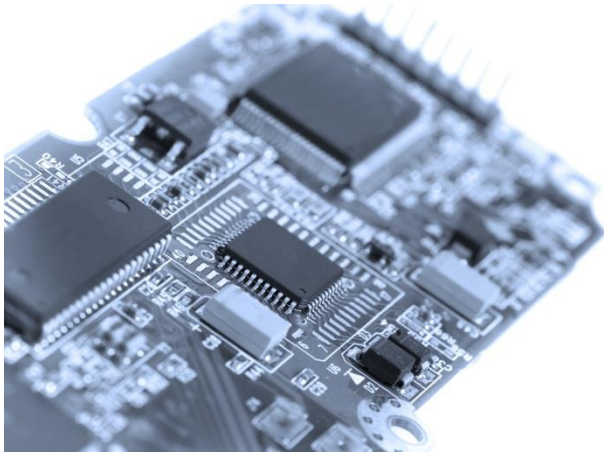
~1987...today



~1910...today



~1950...today





# MICROCHIPS, MEMS UND LED: BUILDING BLOCKS FOR TECHNOLOGICAL PRODUCT ADVANCEMENT

## Digital Lifestyle

- The „Digital Lifestyle“ is characterized by permanent internet connectivity and convergence of media
- Mobile devices like smartphones and tablet PCs provide this capability at affordable cost
- New device generations offer higher functionality



## E-Mobility

- Alternative transportation / mobility solutions are getting more traction with attractive price / performance ratios
- EVs, Hybrid-Cars, Segways, E-Bikes, but also trains drive the need for power devices but also high performance ICs



## Energy Efficiency

- Increase environmental awareness and rising energy prices and fuel the demand for energy efficient solutions in electricity usage i.e. lighting
- Energy efficiency in industrial production
- Smart energy management in household applications saves energy





**With its strong position in the fast growing target markets 3D Integration / Advanced Packaging, LED and MEMS, SUSS MicroTec can benefit from the market developments:**

## **Advanced Packaging**

Wafer level packaging and flip chip is expected to remain more robust than the overall market, primarily driven by mobile devices like smart phones and tablets

## **3D Integration (TSV)**

Transition to production volume in the years to come

## **Compound Semiconductors**

LED, MEMS, RF, Optoelectronics, III-V Power are expected to remain robust based on smartphone and tablet growth and will drive further demand for advanced packaging solutions

**Segment growth 2011 - 2016E CAGR ~ 15%** (Gartner and industry estimates)

# SCALING TECHNOLOGIES FROM 2D TO 3D

## 2D Packaging

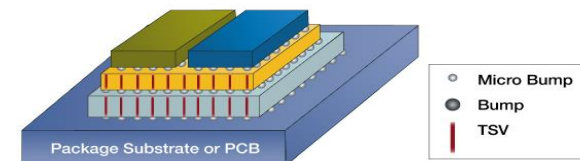
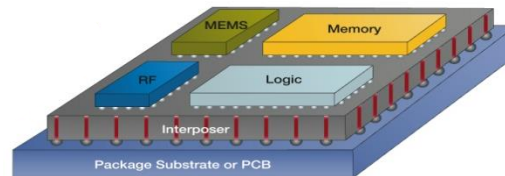
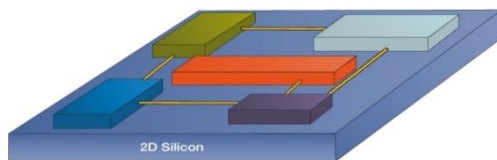
- Increased performance and complexity of ICs by shrinking transistor geometry according to Moore's Law
- New technologies like EUV and multiple patterning allow further scaling
- Technical challenges and limitations make it increasingly more difficult and expensive to reduce the feature size

## 2.5D Packaging

- Combining of several (and heterogeneous) semiconductor components on an interposer addresses limitations of traditional shrinking
- Increased packaging density
- Reduced footprint
- Complementary technology to Moore's Law

## 3D Integration (TSV)

- The extension beyond the conventional shrink roadmap is called "More than Moore"
- Packaging becomes key enabler for scaling and some manufacturing value is shifting from silicon to the package
- Performance and complexity increase combined with smaller footprint
- Reduced energy consumption



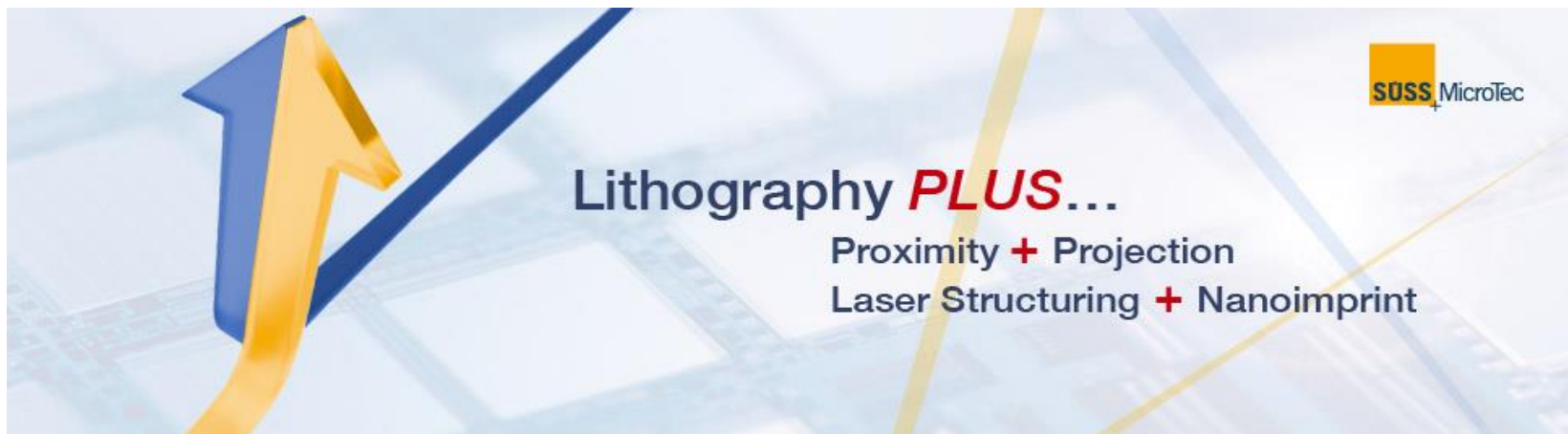
**SUSS MicroTec's equipment and process solutions enable 2D shrinking ("*Moore's Law*") and 3D stacking ("*More than Moore*")**

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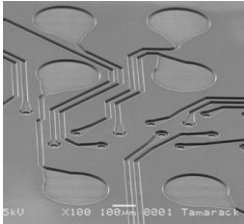


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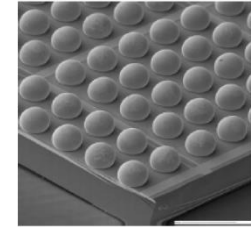
- + Increasing chip performance requires the adoption of innovative lithography technologies in the semiconductor backend
- + **Not one single exposure technology fits all needs at the same time**
- + The newly acquired Stepper/Scanner products supplement our Mask Aligner product line and enlarges our technology portfolio by the key competencies UV-projection lithography and laser ablation
- + SUSS MicroOptics S.A. adds key know how for critical lithography performance improvements



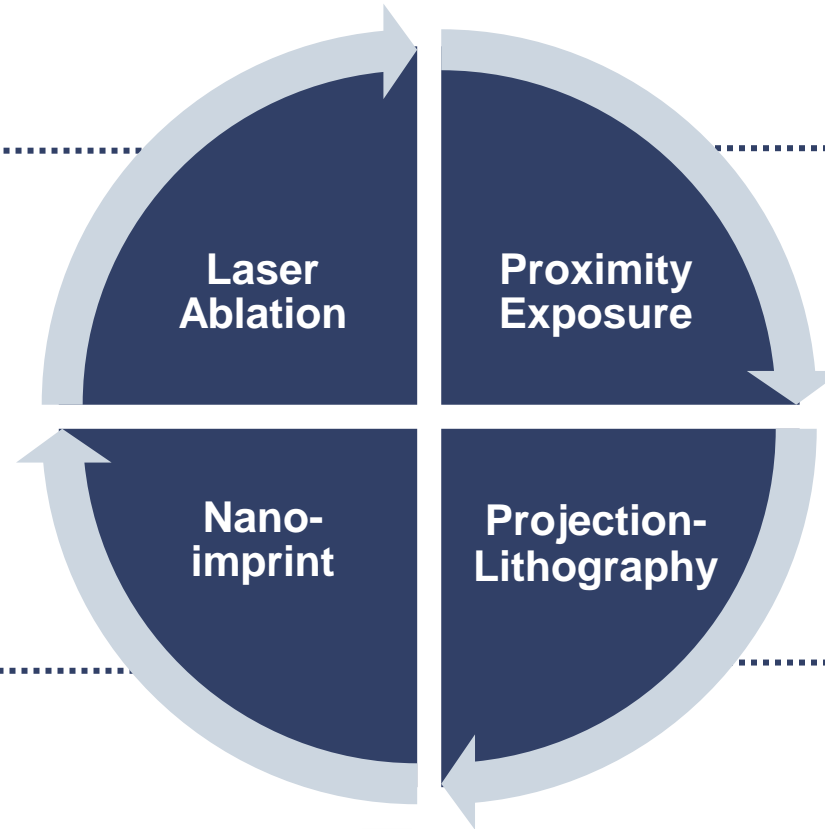




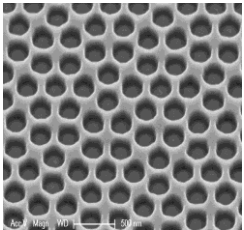
**WLCSP:**  
Fanout WLP



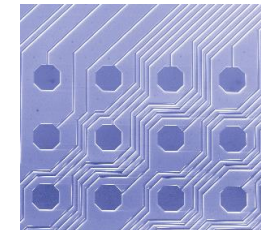
**Flip Chip:**  
Solder Bumping



**LED:**  
Photonic Crystals



**WLCSP:**  
Fine pitch RDL

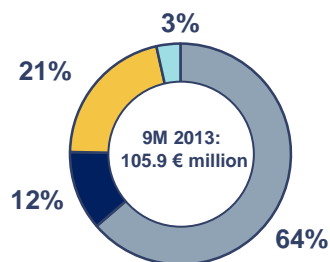


**+ Only SUSS MicroTec offers complete exposure solutions for the mid-/back-end**

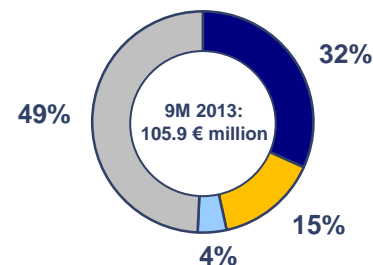
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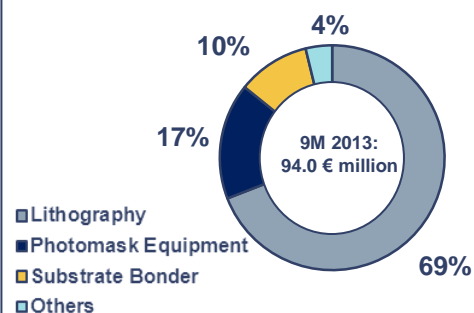
## Order Entry by Segment



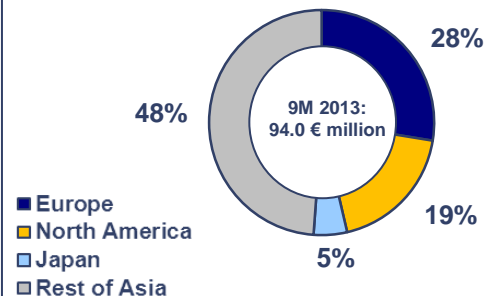
## Order Entry by Region



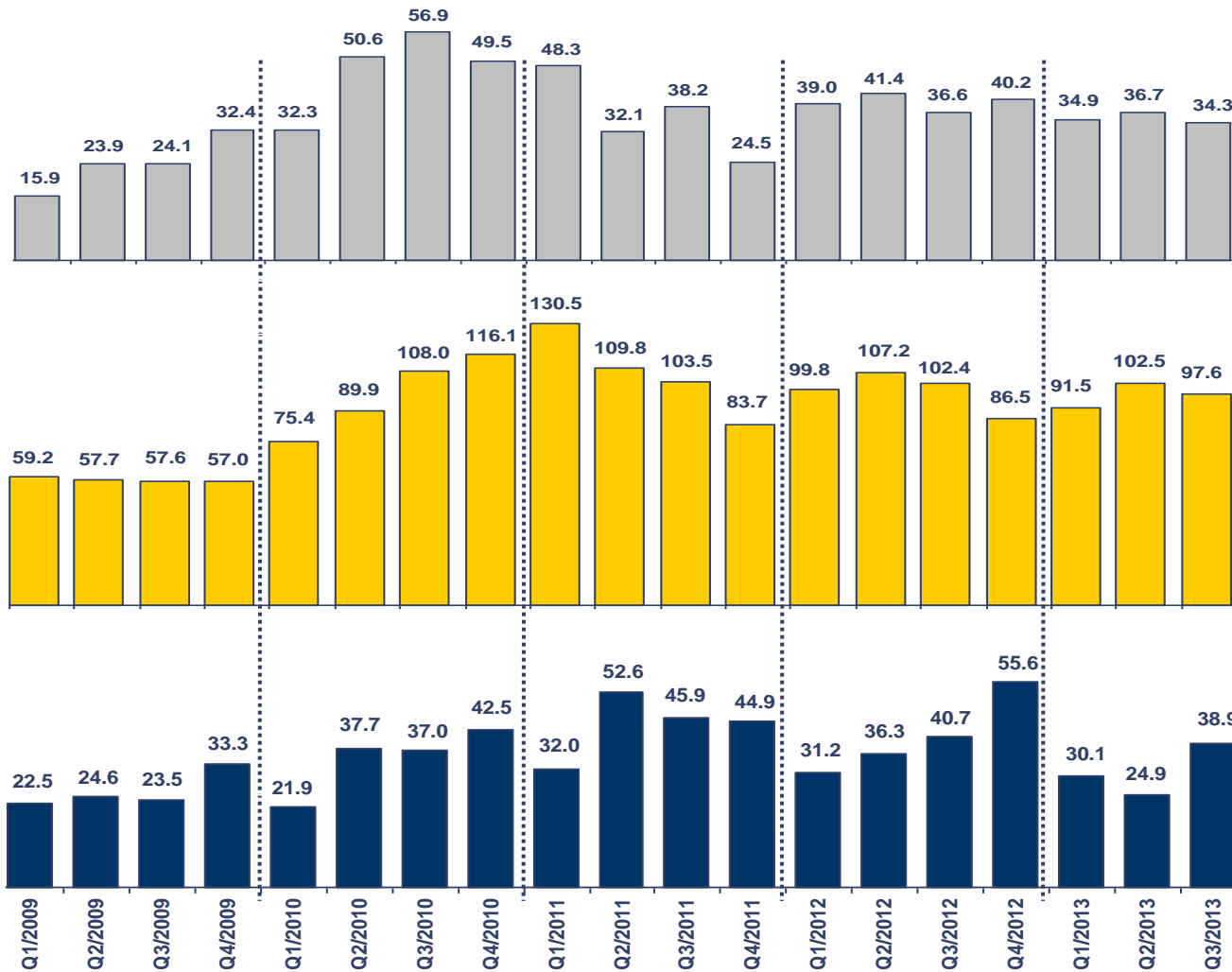
## Sales by Segment



## Sales by Region



# LONG TERM BUSINESS DEVELOPMENT



**Order Entry**

in € million

2012: € 157.2 million

**Order Backlog**

in € million

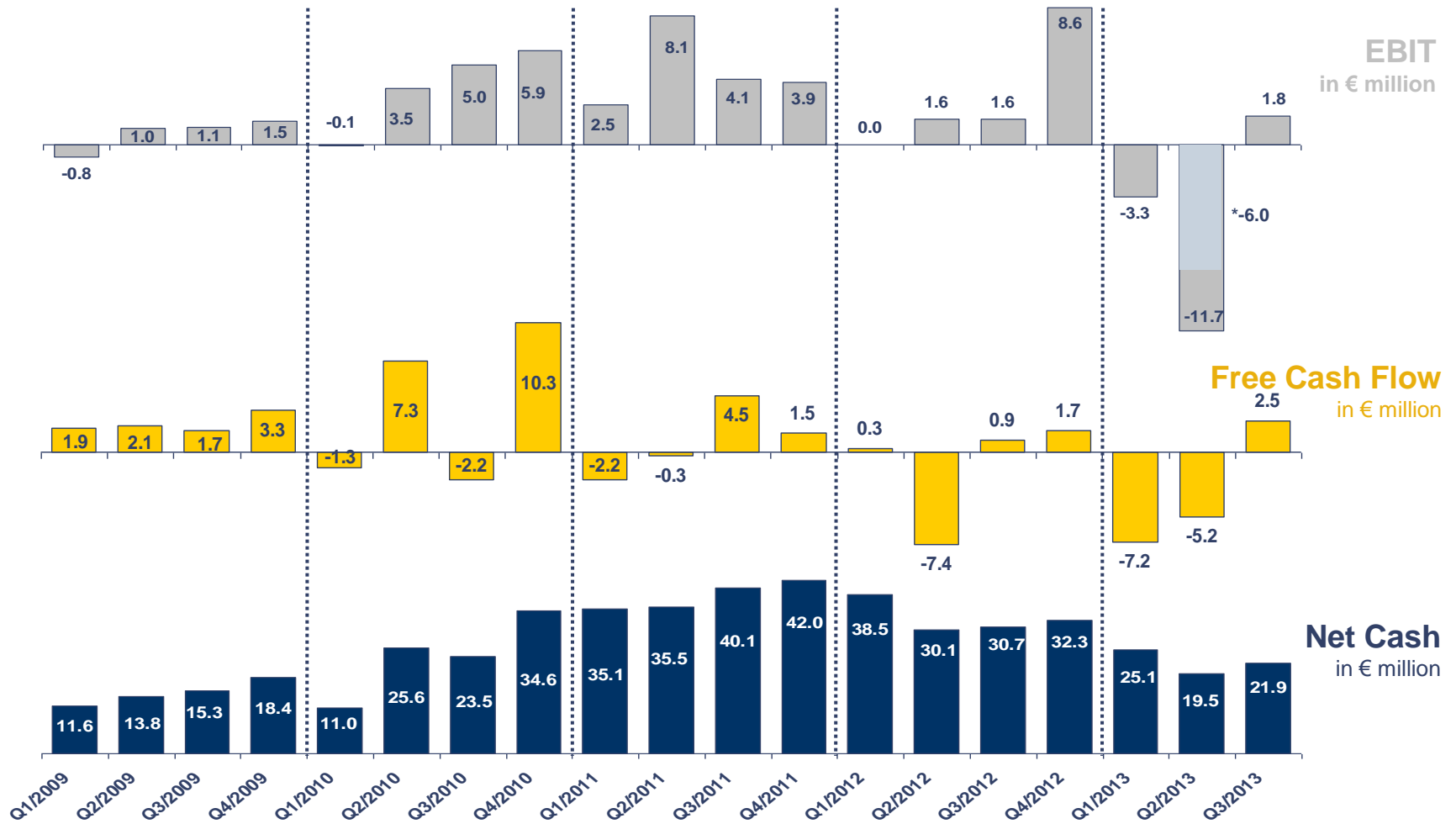
**Sales**

in € million

2012: € 163.8 million



# EBIT, FREE CASH FLOW AND NET CASH DEVELOPMENT



\* one-off effect from refocusing product line permanent bonding

# KEY FINANCIALS

in € million	Q3 2013	Q3 2012	in %	9M 2013	9M 2012
<b>Order Intake</b>	<b>34.3</b>	<b>36.6</b>	<b>-6.3%</b>	<b>105.9</b>	<b>117.0</b>
<b>Order Backlog 9/30</b>	<b>--</b>	<b>--</b>	<b>--</b>	<b>97.6</b>	<b>102.4</b>
<b>Revenue</b>	<b>38.9</b>	<b>40.7</b>	<b>-4.4%</b>	<b>94.0</b>	<b>108.2</b>
<b>EBIT</b>	<b>1.8</b>	<b>1.6</b>	<b>+12.5%</b>	<b>-13.2</b>	<b>3.1</b>
<i>EBIT in % of Sales</i>	<i>4.6%</i>	<i>3.9%</i>	<i>--</i>	<i>-14.0%</i>	<i>2.9%</i>
<b>EBIT (adjusted)</b>	<b>1.8</b>	<b>1.6</b>	<b>+12.5%</b>	<b>-7.2</b>	<b>3.5</b>
<i>EBIT (adjusted) in % of Sales</i>	<i>4.6%</i>	<i>3.9%</i>	<i>--</i>	<i>-7.6%</i>	<i>3.2%</i>
<b>Earnings after tax (continuing operations)</b>	<b>1.2</b>	<b>0.4</b>	<b>&gt;100%</b>	<b>-10.5</b>	<b>0.8</b>
<b>Earnings after tax</b>	<b>1.2</b>	<b>0.4</b>	<b>&gt;100%</b>	<b>-10.5</b>	<b>2.3</b>
<b>EPS in € (continued op.)</b>	<b>0.06</b>	<b>0.02</b>	<b>&gt;100%</b>	<b>-0.55</b>	<b>0.04</b>
<b>Free Cash Flow*</b>	<b>2.5</b>	<b>0.9</b>	<b>&gt;100%</b>	<b>-9.9</b>	<b>-6.2</b>
<b>Net Cash**</b>	<b>--</b>	<b>--</b>	<b>--</b>	<b>21.9</b>	<b>30.7</b>
<b>Employees 9/30</b>	<b>--</b>	<b>--</b>	<b>--</b>	<b>673</b>	<b>699</b>

\* before consideration of purchased interest-bearing securities , the acquisition of Tamarack and the gain out of the sale from the Test Business

\*\* incl. stock of interest-bearing securities

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**2013:**

- Milestone achievement in temporary bonding
- Restructuring of product line Permanent Bonding expanded
- Further integration of SUSS MicroTec Photonic Systems

**Fundamental growth in target markets**

**Strong competitive positioning: first or second in the target markets**

**Leading equipment company in the semiconductor backend, enabling “Moore’s Law” as well as “More than Moore”**

## Outlook

**FY 2013:**

- Sales of 125 – 135 € million
- EBIT: minus 22 – minus 27 million € (thereof 14.3 € million one-off charges)

**Q4 2013:**

- Order Intake 30 - 40 € million
- One-off charges 8.3 € million





Thank you!

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## Contact

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## Financial Calendar 2014

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KeplerCheuvreux Investment Conference, Frankfurt	20.-21. Jan
Annual Report 2013	28 Mar
Quarterly Report 2014	8. May
Shareholders' Meeting, Haus der Bayerischen Wirtschaft, Munich	17 Jun
Interim Report 2014	7 Aug
Nine-month Report 2014	6 Nov

# OUR TECHNOLOGY ENABLES SUSTAINABILITY

## Equipment

- SUSS MicroTec equipment is designed to efficiently use electricity and chemicals
- ReMan, the remanufacturing operation of SUSS MicroTec takes back used equipment and refurbishes it



## Applications

- 3D IC and chip scaling helps reducing energy and material consumption
- LEDs for efficient lighting solutions
- MEMS applications improve performance of mobile devices and conserve energy
- Shift to renewable energies requires more power devices and high-performance ICs (e.g. for solar and wind power systems)
- Laser Ablation in lieu of photolithography (seed layer removal)

## Initiatives

- Partner company of VDMA BlueCompetence initiative, a network of equipment providers in Germany, who are following a sustainable business approach
- Innovative lighting solution in Sternenfels
- Improved climatization system of cleanrooms
- Paperless invoice system

**BLUECOMPETENCE**

**Alliance Member**

Partner der Nachhaltigkeitsinitiative  
des Maschinen- und Anlagenbaus

# SUSS MICROTEC PRODUCT PORTFOLIO



**Photomask Equipment**



**Coater/Developer**



**Wafer Bonders**



**Alignment  
Verification Systems**



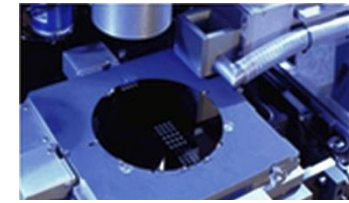
**Mask Aligners**



**Imprinting Systems**



**UV-Projection  
Stepper / Scanner**



**Excimer Laser  
Systems**